



Advances in LTE-M and NB-IoT Chip Technology

Scaling Global Deployment

Dr. Georges Karam

Founder, Chairman, CEO | Sequans Communications



Sequans Communications

Acknowledged Chip Leader in LTE for IoT





Evolution from M2M to IoT

Millions of Things 2G Wireless



Low-power Wireless Connectivity

- Maturity of the technology
- Readiness of the networks
- **⊘** Readiness of the ecosystem: chip/module/device/service

Billions of Things LTE-M & NB-IoT





Sequans is Ready

for Global Deployment

- Monarch is the first genuine LTE-M chip introduced in 2016
- 2017 dedicated to maturing our technology end-to-end and certifying modules and devices
- **Introduced derivative chips:** Monarch SX, Monarch SiP and **CLOE** tracker platform

Certified by AT&T and Verizon in the USA; engaged with carriers worldwide

























Monarch Designed For



LTE for IoT

Low Power

Enables battery life of 1 month for consumer tracker up to 15 years for smart meter

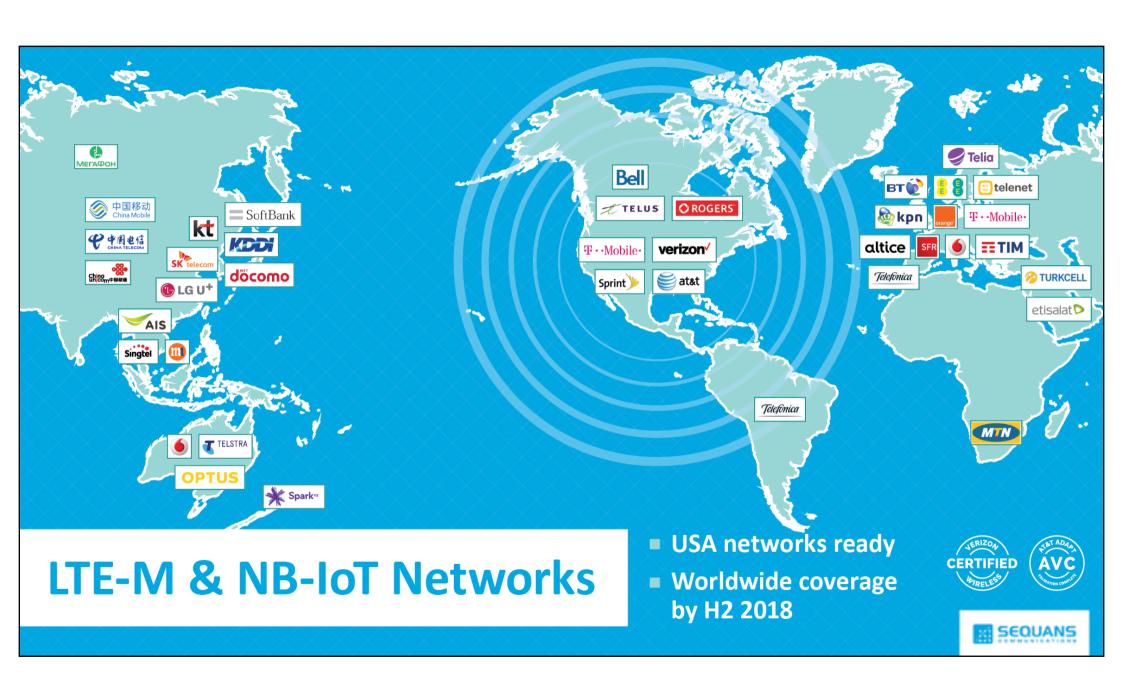
Low Cost

Due to high level of integration, simple BOM, and Single SKU[™] RF front end serving all frequency bands worldwide

Easy Integration

With pre-certified modules; application specific platforms, and native support of cloud





Module Partners







































Devices Ready

Sequans Monarch-based Devices



UPIDO LTE-M & NB-IoT Button





LTE-M Live Button





LTE-M & NB-IoT WAN Button







LTE-M Asset Tracker



Skywire® LTE-M Development Kit





uWhere LTE-M Tracker





Bailong Telematics LTE-M On-Board-Unit





SavTrack® LTE-M Tracker Advanced Metering Infrastructure FAN NB-IoT Unit



LTE-M & NB-IoT Button



LLinkLabs

LTE-M Sensor Suite



Gemtek

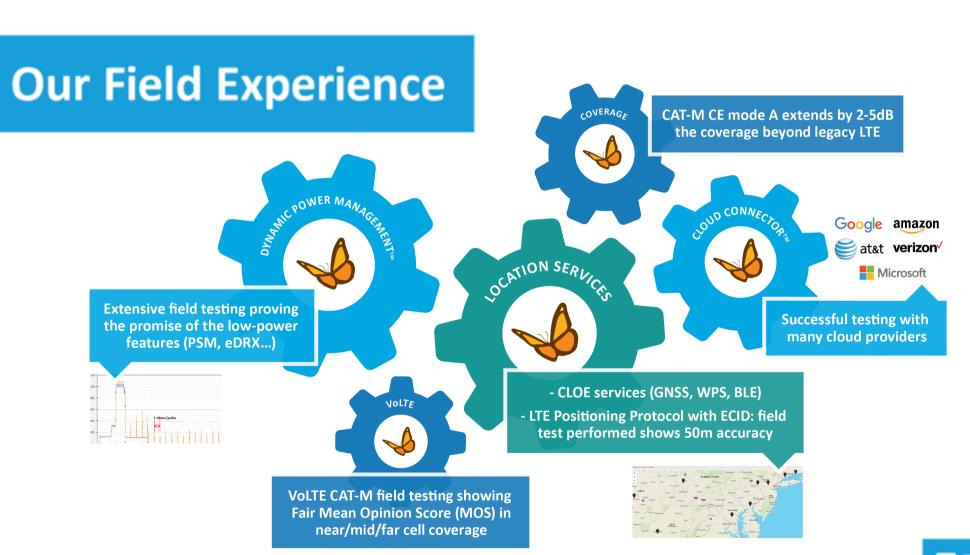
LTE-M WLTSMS
Consumer Tracker





Examples of products publicly announced





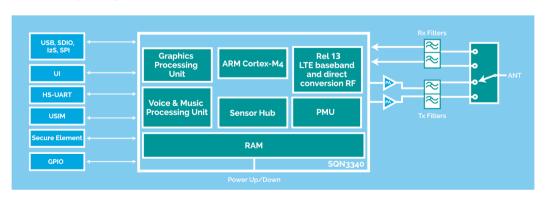


Extending Our Technology Leadership



SoC for Wearables, Feature Phones

- LTE-M & NB-IoT System-on-chip
- **Worldwide Single-SKU**
- **Sampling Now**





Extending Our Technology Leadership



All-in-one System-in-package LTE-M and NB-IoT for Ultra-compact Devices

All-in-one SiP from



- Ultra Small and Thin8.8 mm X 10.8 mm X 0.95 mm
- Every Major Component for LTE-M or NB-IoT Modem System
- **Extremely Reduced RBOM**
- Worldwide Single-SKU
- Leveraging Monarch Carrier Certifications
- Sampling Now





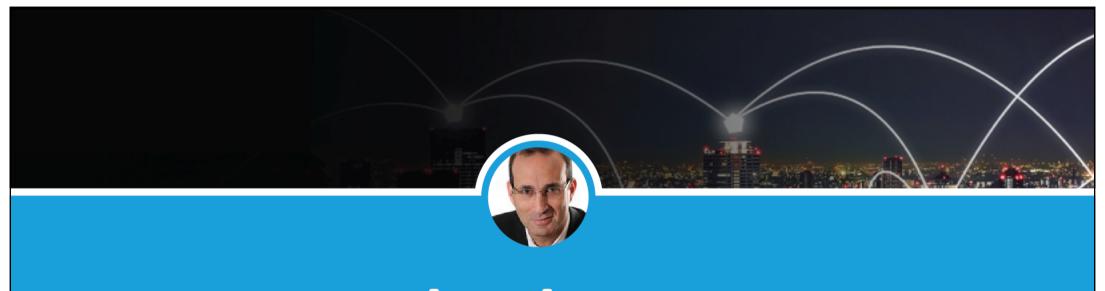
Extending Our Technology Leadership



Ultra Integrated Chip for Pure NB-IoT Operation

- Optimized NB-IoT Chip for Massive IoT
- 3GPP Release 14 and Upgradable to Release 15
- Extremely Reduced BOM
- Ultra Low Power Consumption
- Worldwide Single-SKU





Thank You

Dr. Georges Karam

Founder, Chairman, CEO | Sequans Communications

